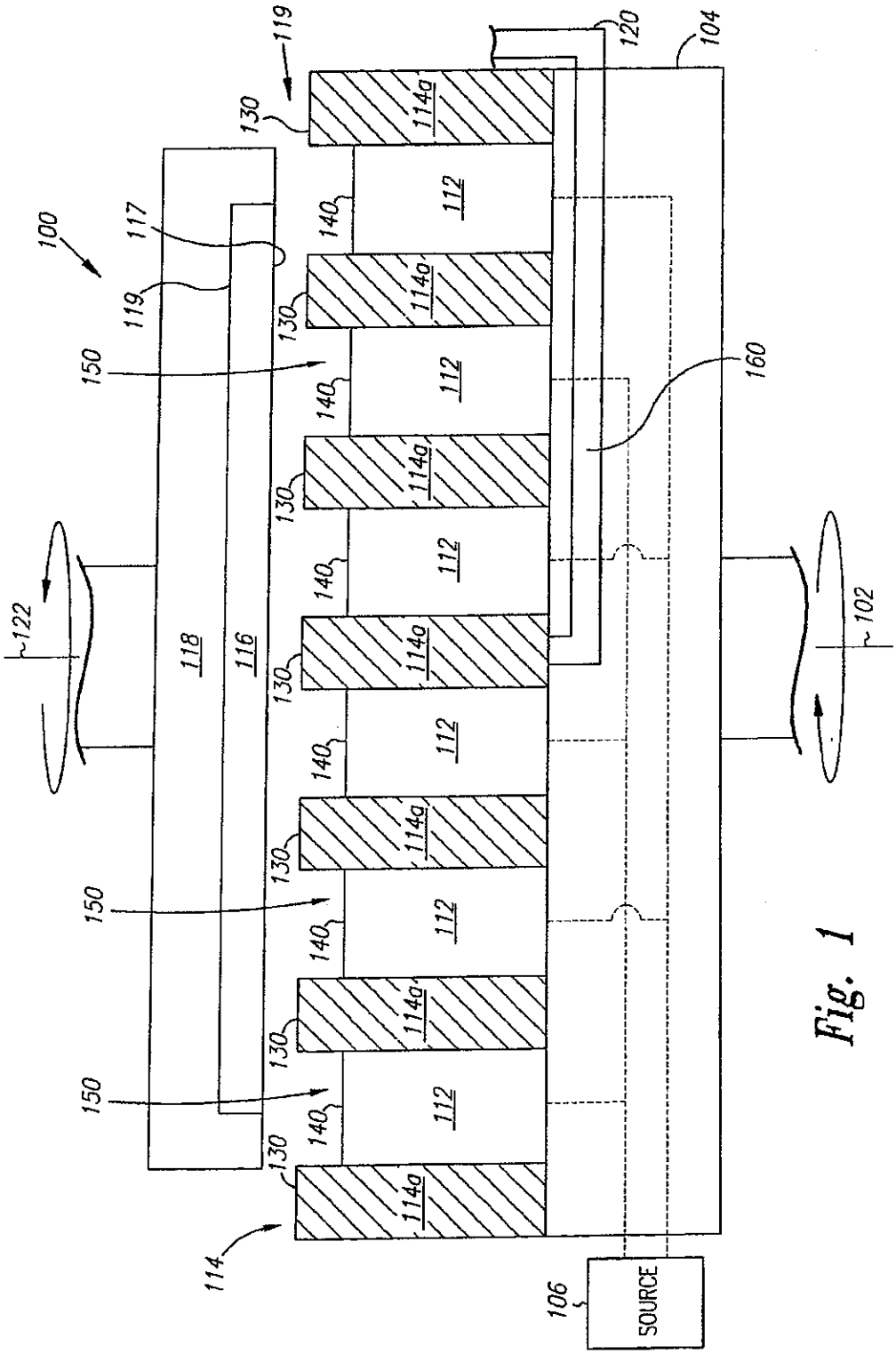

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Fig. 1

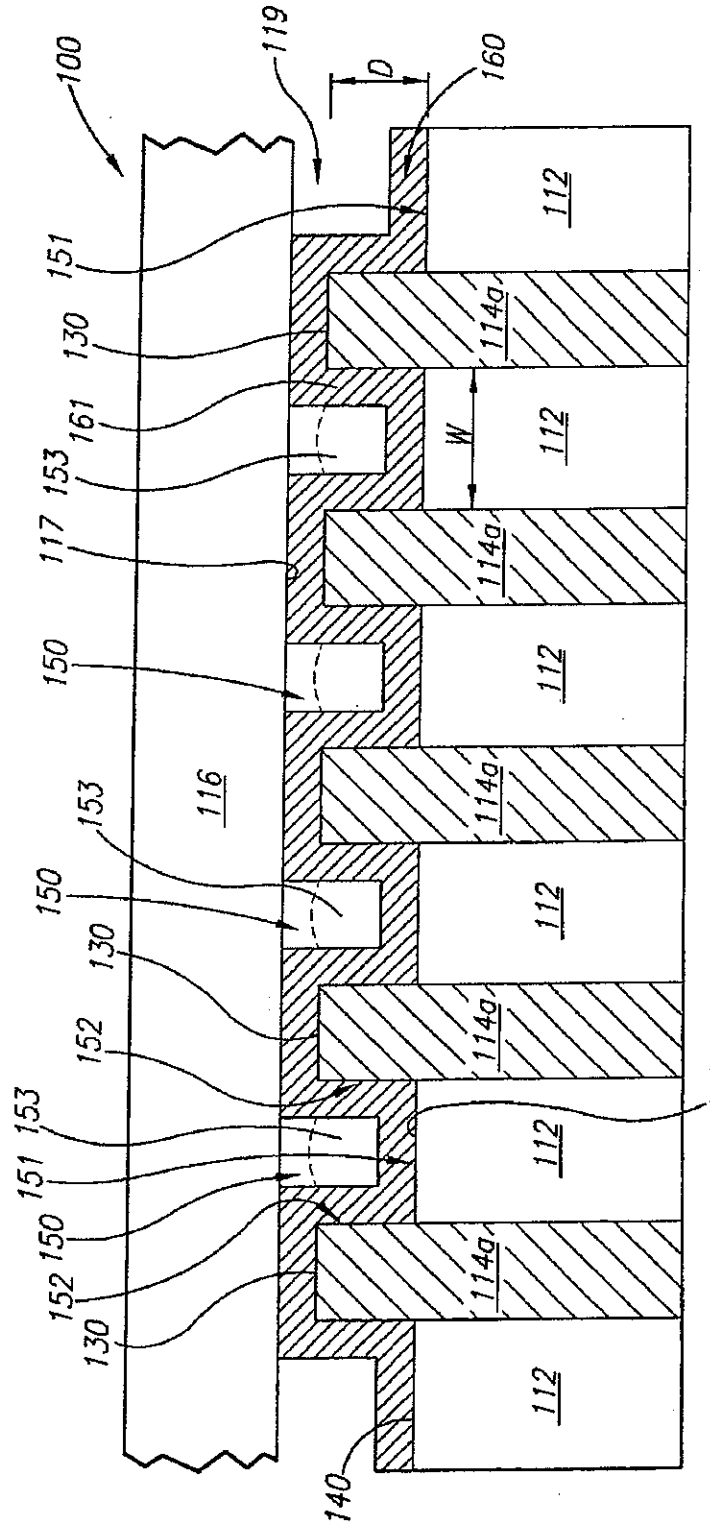

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Fig. 2

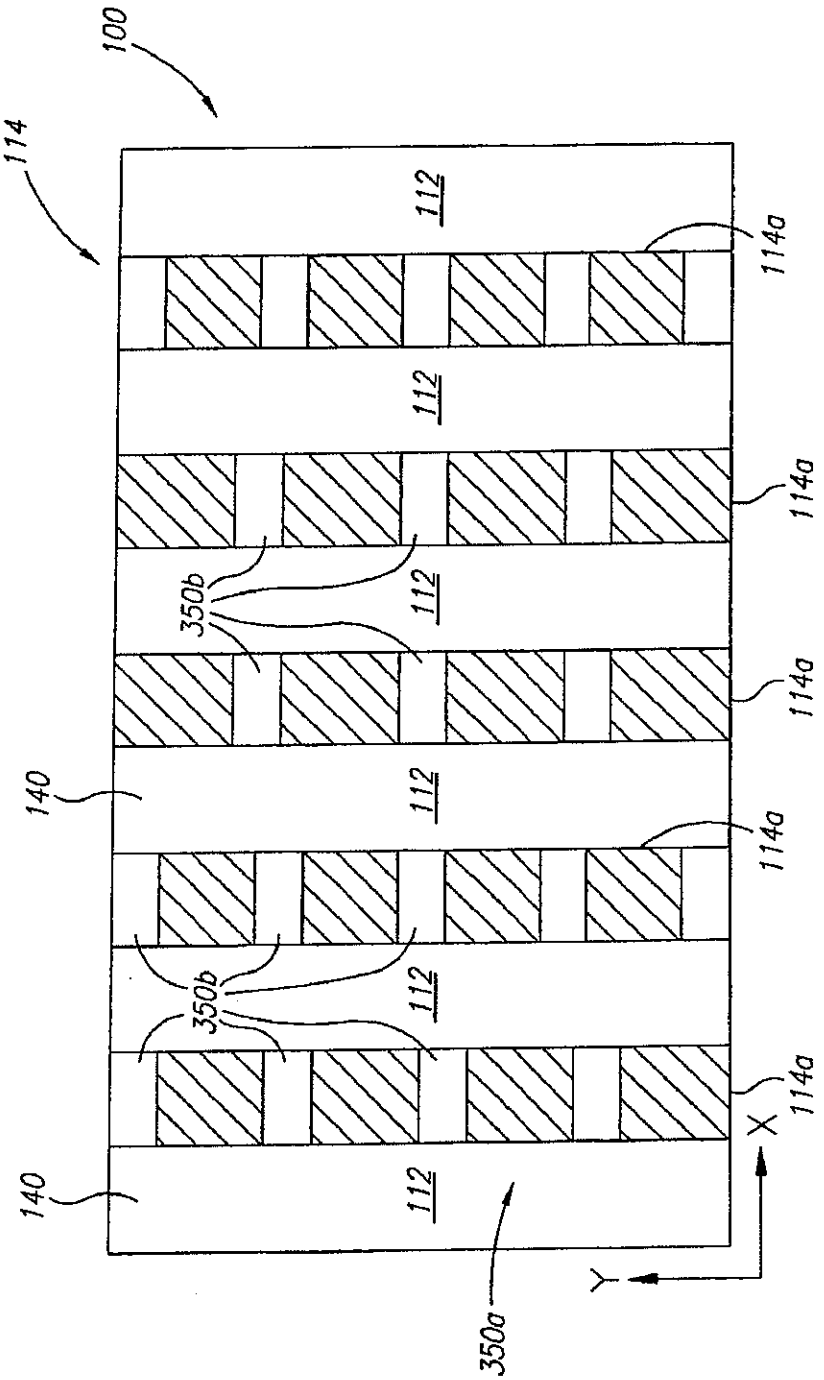


Fig. 3

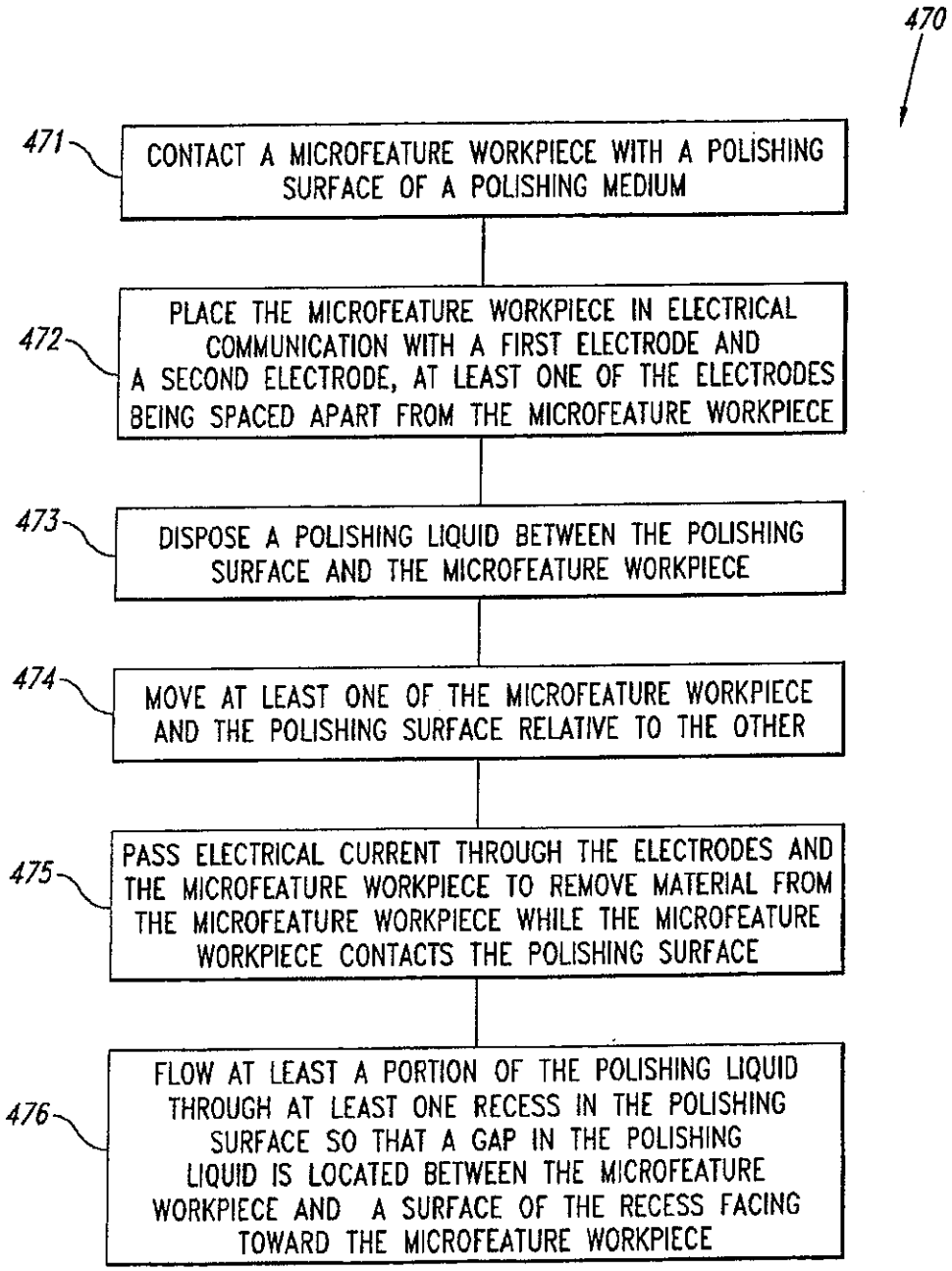

470
471
CONTACT A MICROFEATURE WORKPIECE WITH A POLISHING SURFACE OF A POLISHING MEDIUM
472
PLACE THE MICROFEATURE WORKPIECE IN ELECTRICAL COMMUNICATION WITH A FIRST ELECTRODE AND A SECOND ELECTRODE, AT LEAST ONE OF THE ELECTRODES BEING SPACED APART FROM THE MICROFEATURE WORKPIECE
473
DISPOSE A POLISHING LIQUID BETWEEN THE POLISHING SURFACE AND THE MICROFEATURE WORKPIECE
474
MOVE AT LEAST ONE OF THE MICROFEATURE WORKPIECE AND THE POLISHING SURFACE RELATIVE TO THE OTHER
475
PASS ELECTRICAL CURRENT THROUGH THE ELECTRODES AND THE MICROFEATURE WORKPIECE TO REMOVE MATERIAL FROM THE MICROFEATURE WORKPIECE WHILE THE MICROFEATURE WORKPIECE CONTACTS THE POLISHING SURFACE
476
FLOW AT LEAST A PORTION OF THE POLISHING LIQUID THROUGH AT LEAST ONE RECESS IN THE POLISHING SURFACE SO THAT A GAP IN THE POLISHING LIQUID IS LOCATED BETWEEN THE MICROFEATURE WORKPIECE AND A SURFACE OF THE RECESS FACING TOWARD THE MICROFEATURE WORKPIECE

Fig. 4